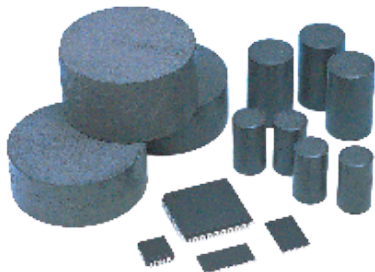


# High Thermal Conductivity EMC

for power module KE-G1250HT-DS



Epoxy molding compound

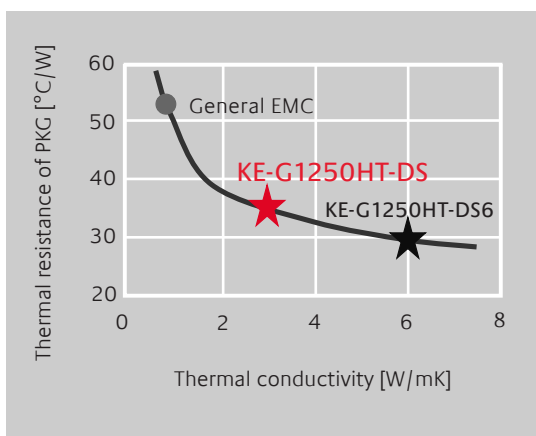


Package image

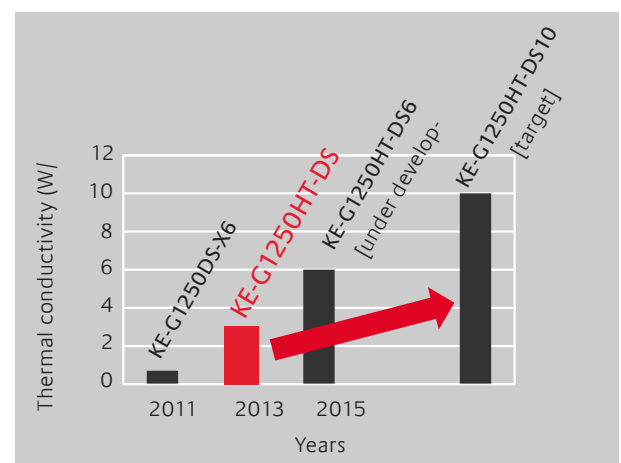
## FEATURES

- ▶ High thermal conductivity
- ▶ High T<sub>g</sub>
- ▶ Good dimension stability
- ▶ Good adhesion strength
- ▶ Good flowability
- ▶ Green material

## Thermal Conductivity vs Thermal Resistance



## Roadmap



## General Properties

Item	Unit	KE-G1250HT-DS
Spiral flow (175°C)	cm	110
Gel time	s	30
Flow viscosity	Pa · s	25
CTE α 1	ppm/°C	13
CTE α 2	ppm/°C	45
T <sub>g</sub>	°C	200
Thermal conductivity	W/m · K	3